

Material Features:

- Low Density
- Low thermal resistance
- Good thermal stability

Applications

- Graphic Processors
- Base stations
- Microprocessors
- Data Centers

Storage Conditions:

- Store in dark environment
- Storage Temperature: $\leq 30^{\circ}\text{C}$
- Storage Humidity: $\leq 70\%$

Shelf Life:

- Stored at storage conditions:
Two years

Short Term Operating Temperature:

- 500°F (260°C) for 30 minutes.

How to Order Product to Size:

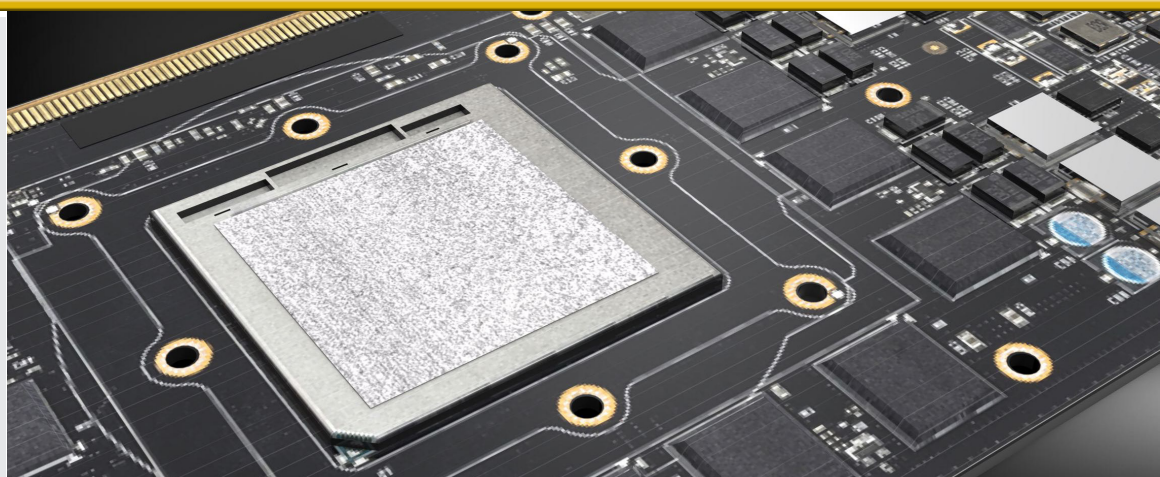
WWWW = Width in inches (ex $5.00'' = 0500$)

LLLL = Length in inches (ex $10.00'' = 1000$)

TTT = Thickness in inches (ex. $0.040'' = 040$)

Example: TCF160-05001000-040

Part numbers will be provided in inches



TGN Series

Leader Tech's TGN series are a new ultra-thin thermal pad with low thermal resistance. This thermal pad is fabricated by combining graphene and silicone. The materials are arranged in the polymer matrix in an orderly manner to form a good thermally conductive path, which greatly improves the efficiency of heat conduction. In addition, this material has high resiliency and low density which can be used as a replacement of thermal grease material.

Part Series	Test Method	TGN700	TGN900	TGN1300
Thermal Properties				
Thermal Conductivity Z axis (W/m-K)	ASTM D 5470	70	90	130
Thermal Conductivity X axis (W/m-K)	ASTM D 5470	600	600	600
Thermal Conductivity Y axis (W/m-K)	ASTM D 5470	25	25	25
Thermal Impedance ($^{\circ}\text{C-in}^2/\text{W}$; @50psi)	ASTM D 5470	≤ 0.090	≤ 0.070	≤ 0.050
Physical Properties				
Color	Visual	Black	Black	Black
Thickness Range (in, (mm))	ASTM D 374	0.008-0.031 (0.2-0.8)	0.008-0.031 (0.2-0.8)	0.008-0.020 (0.2-0.5)
Width & Length (in, (mm))	N/A	3.54 x 3.54 (90 x 90)	3.54 x 3.54 (90 x 90)	1.57 x 1.57 (40 x 40)
Density (lb/in ³ , (g/cc))	ASTM D 792	0.022 (0.6)	0.022 (0.6)	0.036 (1)
Compression Ratio @50 psi (%)	ASTM C 165	≥ 50	≥ 50	≥ 25
Compression Stress @50% (psi)	ASTM D 575	≤ 60	≤ 60	≤ 150
Tensile Strength (M Pa)	ASTM D 412	≥ 0.05 X axis ≥ 0.02 Y axis	≥ 0.05 X axis ≥ 0.02 Y axis	≥ 0.05
Resilience (%)	ASTM D 575	≥ 60	≥ 60	≥ 70
Operating Temperature($^{\circ}\text{F}$ (C))	IEC60068-2-14	-40 to 302 (-40 to 150)	-40 to 302 (-40 to 150)	-40 to 302 (-40 to 150)
Shelf Life (Months)	N/A	24	24	24

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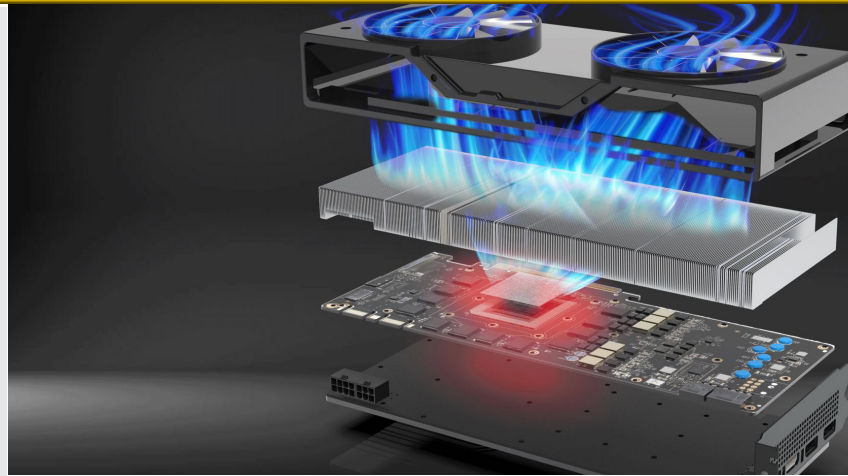
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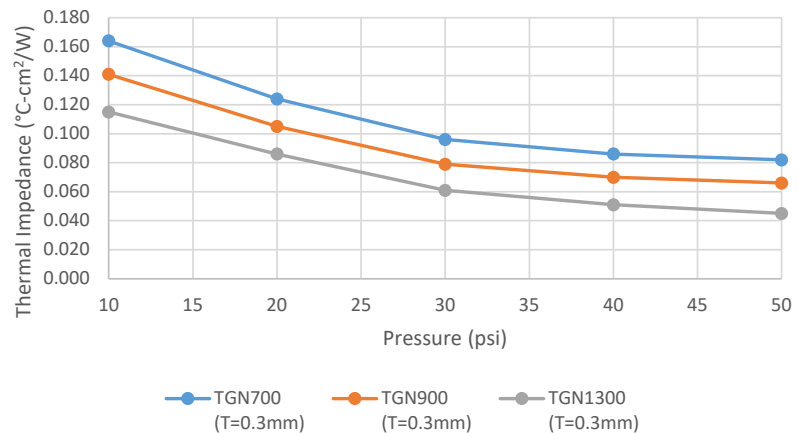
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Thermal Impedance



Compression Ratio

